



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma5k3f35i3

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Electrical Characteristics Page 5

Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
V_{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

Page 6 Electrical Characteristics

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
t	Power supply ramp time	Standard POR	200 μs	_	100 ms	_
LRAMP	Fower supply rainp line	Fast POR	200 μs	_	4 ms	_

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V_{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Treceiver arialog power supply (left side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	

Electrical Characteristics Page 15

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

I/O Standard	V _{IL(D(}	; ₎ (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{ol} (mA)	l _{oh}
i/O Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I _{OI} (IIIA)	(mA)
HSTL-18 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-15 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCIO}	0.75* V _{CCIO}	8	-8
HSTL-12 Class II	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCIO}	0.75* V _{CCIO}	16	-16
HSUL-12	_	V _{REF} – 0.13	V _{REF} + 0.13	_	V _{REF} – 0.22	V _{REF} + 0.22	0.1* V _{CCIO}	0.9* V _{CCIO}	_	

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V _{CCIO} (V)		V _{SWIN}	_{G(DC)} (V)		V _{X(AC)} (V)		V _{SWING(}	_{AC)} (V)
I/O Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCIO} + 0.6	V _{CCIO} /2 – 0.2	_	V _{CCIO} /2 + 0.2	0.62	V _{CCIO} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO} + 0.6	V _{CCIO} /2 – 0.175	_	V _{CCIO} /2 + 0.175	0.5	V _{CCIO} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V _{CCIO} /2 – 0.15	_	V _{CCIO} /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V _{CCIO} /2 – 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V _{CCIO} /2 – 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V _{REF} -0.15	V _{CCIO} /2	V _{REF} + 0.15	-0.30	0.30

Note to Table 20:

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 1 of 2)

I/O		V _{CCIO} (V)		V _{DIF(}	_{DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)	V _{DIF(}	_(C) (V)
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2		0.68	_	0.9	0.68		0.9	0.4	_

⁽¹⁾ The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits $(V_{IH(DC)})$ and $V_{IL(DC)})$.

Electrical Characteristics Page 17



You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade		Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit Ω Ω Ω Ω mV mV μs μs
	85– Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-	100–Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	_	100 ± 30%	_	Ω
chip termination resistors (21)	120–Ω setting	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
	V _{CCR_GXB} = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
V _{ICM} (AC and DC	V _{CCR_GXB} = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupled)	V _{CCR_GXB} = 1.0 V/1.05 V full bandwidth	_	700	_	_	700	_	_	700	_	mV
	V _{CCR_GXB} = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t _{LTR} (11)	_	_	_	10	_	_	10	_	_	10	μs
t _{LTD} (12)	_	4	_		4			4		_	μs
t _{LTD_manual} (13)	_	4	_		4	_		4	_		μs
t _{LTR_LTD_manual} (14)	_	15	_	_	15		_	15		_	μs
Run Length	_		_	200		_	200	_		200	UI
Programmable equalization (AC Gain) ⁽¹⁰⁾	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

Page 24 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_		_	10	_	_	10	_	_	10	μs

Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{I TD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll\ powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{nll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{REF} is 2000 Ω ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Page 26 Switching Characteristics

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode ⁽²⁾	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

⁽³⁾ The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Page 28 Switching Characteristics

Table 27 shows the $\ensuremath{V_{OD}}$ settings for the GX channel.

Table 27. Typical V $_{\text{OD}}$ Setting for GX Channel, TX Termination = 100 Ω $^{(2)}$

Symbol	V _{OD} Setting	V _{op} Value (mV)	V _{op} Setting	V _{op} Value (mV)
	0 (1)	0	32	640
	1 (1)	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 ⁽¹⁾	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
V op differential peak to peak	15	300	47	940
typical ⁽³⁾	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

Note to Table 27:

- (1) If TX termination resistance = 100Ω , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

Page 30 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	5
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1L, 1.4-V PC	ML, 1.5-V P(CML, 2.5-V I and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS
otandardo	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	3
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz
Rise time	20% to 80%	_	_	400	_	_	400	
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps
Duty cycle	_	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4	_	_	-0.4		_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	0/0.9/0.85	(22)	V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCML	, 1.5-V PCML	_, 2.5-V PCI	ML, LVPEC	L, and LVDS	6
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration (16), (20)	$V_{CCR_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
oomiguration ', ' /	GX channels				(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

Page 38 Switching Characteristics

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

		Performance		
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit
Global and Regional Clock	717	650	580	MHz
Periphery Clock	550	500	500	MHz

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 2 of 2)

		Resour	ces Used			Pe	erforman	ce			
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Tei	mperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°	°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	_	200	μΑ
V _{bias,} voltage across diode	0.3	_	0.9	V
Series resistance	_	_	<1	Ω
Diode ideality factor	1.006	1.008	1.010	_

⁽¹⁾ To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

⁽²⁾ When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

⁽³⁾ The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Page 44 Switching Characteristics

Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.



The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

_														
Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I	4	Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{HSCLK_in} (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 (4)	5		800	5	_	800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards (3)	Clock boost factor W = 1 to 40 (4)	5		800	5	_	800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (4)	5		520	5	_	520	5		420	5		420	MHz
f _{HSCLK_OUT} (output clock frequency)	_	5		800	5	_	800	5		625 (5)	5		525 (5)	MHz

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I4	4	IIi.
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

Page 50 Switching Characteristics

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Notes to Table 40:

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 1 of 2) (2), (3)

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t _{JIT(per)}	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	t _{JIT(cc)}	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t _{JIT(per)}	-75	75	- 75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	t _{JIT(cc)}	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	t _{JIT(duty)}	- 75	75	-75	75	-90	90	-90	90	ps

⁽¹⁾ This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a −2 speed grade is ±78 ps or ±39 ps.

Page 58 Configuration Specification

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μ\$
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1,506 ⁽³⁾	μ\$
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μ\$
t _{ST2CK} (6)	nSTATUS high to first rising edge of DCLK	2	_	μ\$
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _{CD2UM}	CONF_DONE high to user mode (4)	175	437	μS
+	GOVER DOVER high to GUVERN anabled	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁵⁾	_	_

Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

Page 60 Configuration Specification

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 $^{(1)}$

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nconfig high to nstatus high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾	_	S
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _R	Input rise time	_	40	ns
t _F	Input fall time	_	40	ns
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the t_{status} specification. If nstatus is not monitored, follow the t_{cfack} specification.

Page 62 Configuration Specification

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

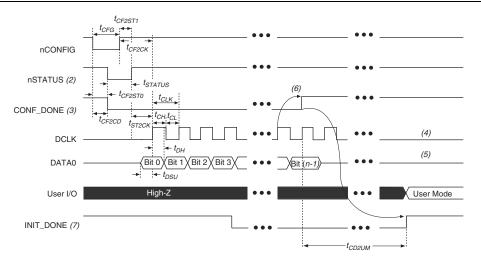
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Page 72 Document Revision History